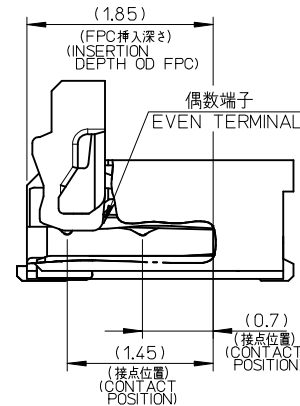
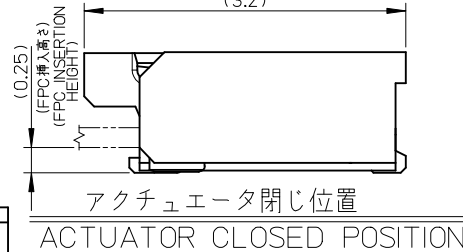
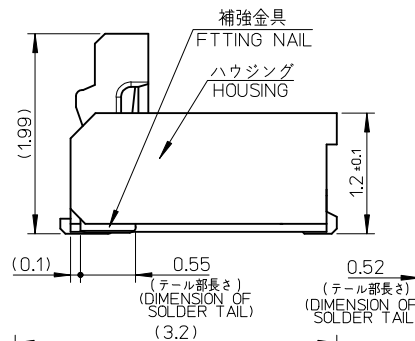
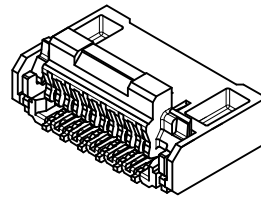
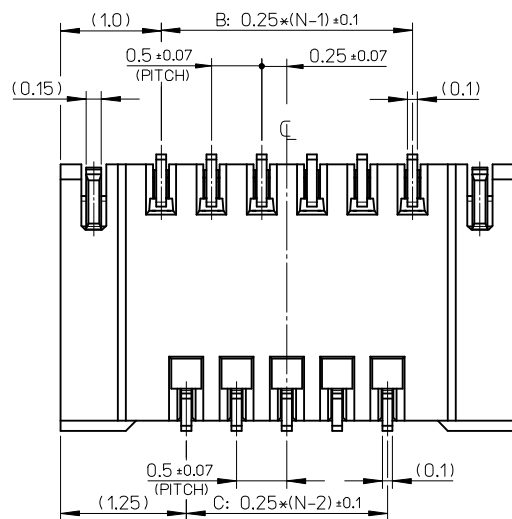
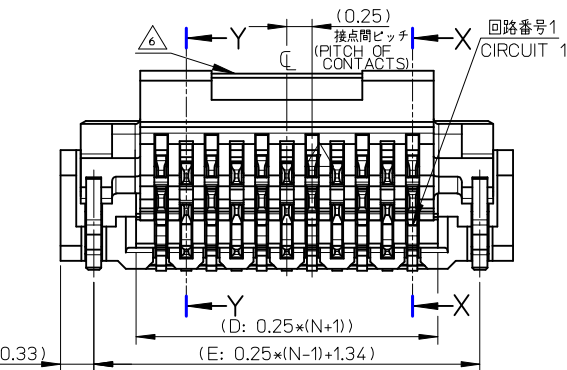
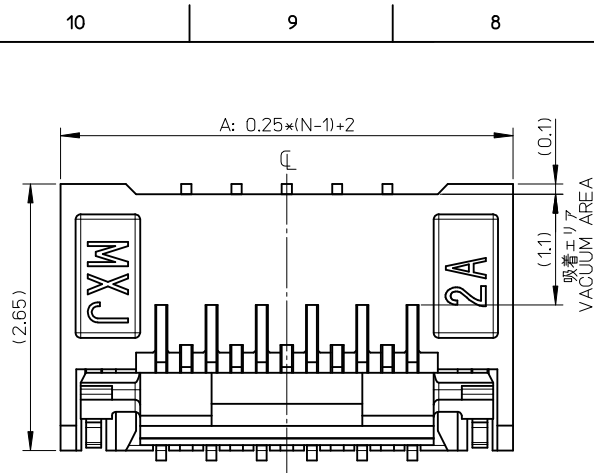
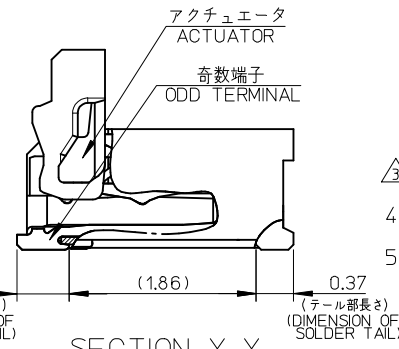




SECTION Y-Y



SECTION X-X

注記 NOTES

1. 使用材料 MATERIALS

ハウジング : 液晶ポリマー(UL94V-0、黒色)
 アクチュエータ : ポリアミド樹脂(UL94V-0、ベージュ)
 奇数端子 : リン青銅
 偶数端子 : リン青銅
 補強金具 : リン青銅
 HOUSING : G.F. LCP (BLACK)
 ACTUATOR : G.F. POLYAMIDE (BEIGE)
 ODD TERMINAL : PHOSPHOR BRONZE
 EVEN TERMINAL : PHOSPHOR BRONZE
 FITTING NAIL : PHOSPHOR BRONZE

2. メッキ仕様 PLATING

端子 TERMINAL

テール部 : 金メッキ
 接点部 : 金メッキ0.1μm以上
 下地 : ニッケルメッキ1.0μm以上
 TAIL AREA : Gold PLATING
 CONTACT AREA : Gold PLATING 0.1μm MINIMUM
 UNDER PLATING : Nickel PLATING 1.0μm MINIMUM

金具 FITTING NAIL

全面 : スズメッキ 1.0μm 以上
 下地 : ニッケルメッキ 1.0μm 以上
 ALL OVER : Tin PLATING 1.0μm MINIMUM
 UNDER PLATING : Nickel PLATING 1.0μm MINIMUM

△ 端子、補強金具のコプラナリティーは 0.1 以下とする
 COPLANALITY OF SOLDER TAILS AND FITTING NAILS : 0.1MAX.

4. 一般公差 : ± 0.3
 GENERAL TOLERANCES: ±0.3

5. ELV 及び RoHS 適合品
 ELV AND RoHS COMPLIANT

△ ゲート部形状とする
 本形状は極数により異なります
 THIS SHAPE IS FOR GATE
 IT DEPENDS ON THE NUMBER OF CIRCUITS

14.34	13.5	12.5	13	15	503300-5310	53
11.84	11	10	10.5	12.5	503300-4310	43
11.34	10.5	9.5	10	12	503300-4110	41
10.34	9.5	8.5	9	11	503300-3710	37
8.84	8	7	7.5	9.5	503300-3110	31
8.34	7.5	6.5	7	9	503300-2910	29
6.34	5.5	4.5	5	7	503300-2110	21
E	D	C	B	A	ORDER NO. EMBOSSED TAPE PACKAGE	CIRCUITS

CONNECTOR SERIES NO.

503300-**18

GENERAL TOLERANCES
(UNLESS SPECIFIED)

DIMENSION STYLE
MM ONLY

SCALE
20:1

DESIGN UNITS
METRIC

THIRD ANGLE
PROJECTION

10 UNDER	± ---
10 OVER 30 UNDER	± ---
30 OVER	± ---

ANGULAR ±1 °

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DRAWN BY DATE

DATE

CHECKED BY DATE

DATE

APPROVED BY DATE

DATE

MATERIAL NO.

SEE CHART

SIZE A3

TITLE

0.25 PITCH FPC CONN. E/O
HGT=1.2 UPR CONTACT TYPE
LOW-HALOGEN

molex

DOCUMENT NO.

SD-503300-001

SHEET NO.

1 OF 2

F

E

D

C

B

A

F

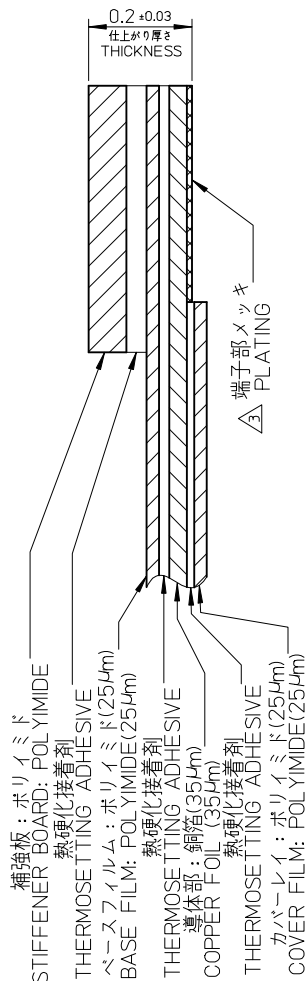
E

D

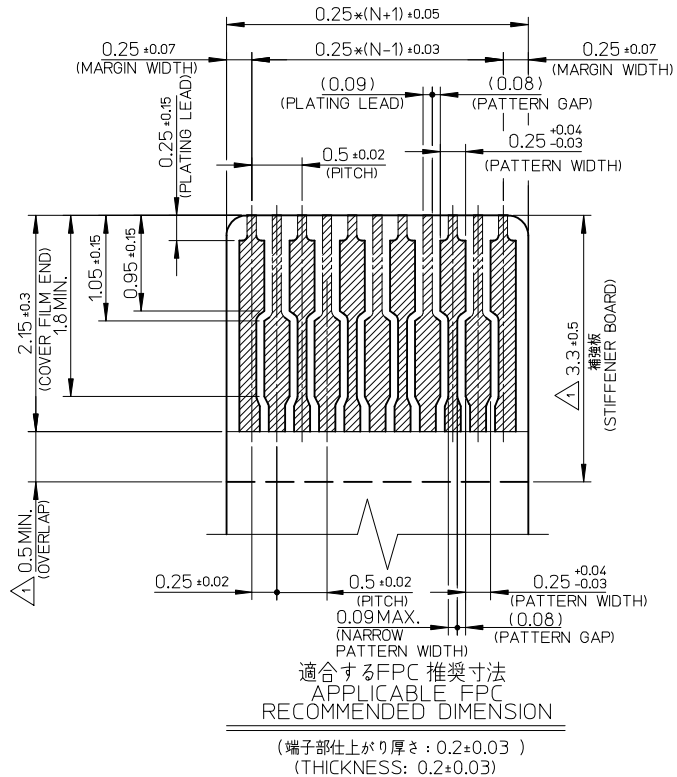
C

B

A



FPC 構成材料例
EXAMPLE OF FPC
COMPOSITION MATERIAL

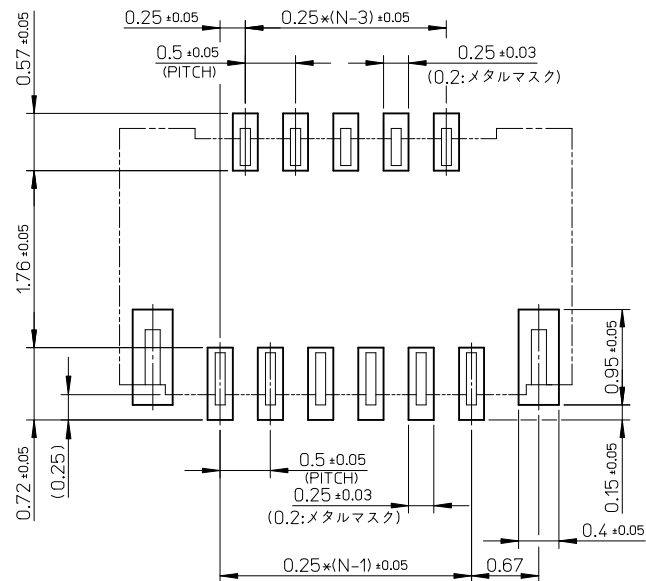


注記 NOTES

- △ 補強板長さが図面通り確保できない場合は、カバーレイと補強板のオーバーラップ寸法を 0.5mm 以上としてください
WHEN STIFFENER BOARD DIMENSION CAN NOT SECURE AS DRAWING, PLEASE GIVE THE OVERLAP SIZE OF COVER FILM AND STIFFENER BOARD AS 0.5mm MINIMUM
- 2 推奨ペースト厚 : 100μm
推奨マスク開口率 : 80%
RECOMMEND SCREEN THICKNESS : 100μm
RECOMMEND SCREEN OPEN RATIO : 80%

- △ 3 FPCパターンのメッキ仕様は
金メッキ : 0.1μm 以上
下地ニッケルメッキ : 2~6μm
FPC PATTERN PLATING
GOLD PLATING : 0.1μm MINIMUM
NICKEL UNDER PLATING : 2~6μm

- 4 FPCについて (ABOUT FPC)
抜き方向は、導体側から補強板側を推奨します
補強板材質は、ポリイミドを推奨します
接着剤は熱硬化接着剤を推奨します
なお、接着剤の接点部への付着は導通不良の原因となりますので染み出しがないよう、お願いします
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE
RECOMMENDED MATERIAL:
STIFFENER BOARD: POLYIMIDE
BONDING AGENT: THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON THE CONTACT AREA BECAUSE THE EXTRA ADHESIVE MAY CAUSE THE DEFECT IN ELECTRICAL CONTINUITY

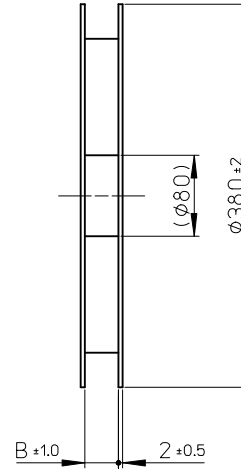
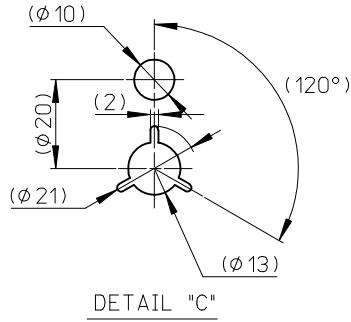
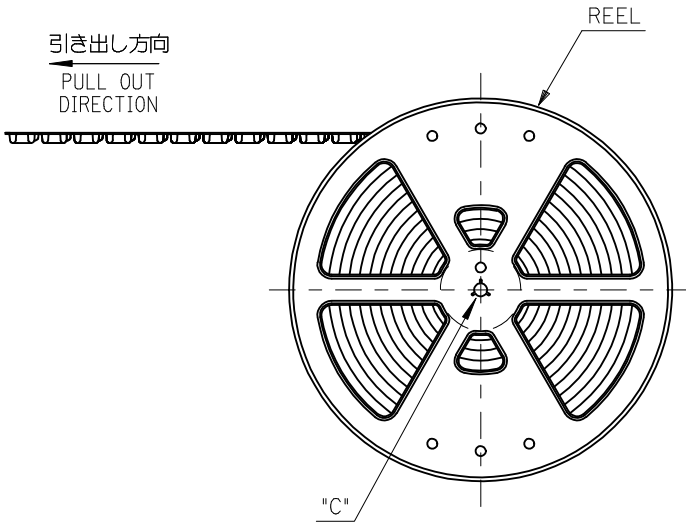


REVISED EC NO.: J2014-1201 DRAWN: TMORI/SHITA CHK'D: K TAKAHASHI APPR: YNOGAWA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 20:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	DRAWN BY MNIITA	DATE 2010/08/23	TITLE 0.25 PITCH FPC CONN. E/O HGT=1.2 UPR CONTACT TYPE LOW-HALOGEN				
		10 OVER 30 UNDER	± ---	CHECKED BY SHOSHIKAWA	DATE 2010/08/24					
		30 OVER	± ---	APPROVED BY SHOSHIKAWA	DATE 2010/08/27	molex				
		ANGULAR ±1 °		MATERIAL NO. SEE SHEET1						
REV		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

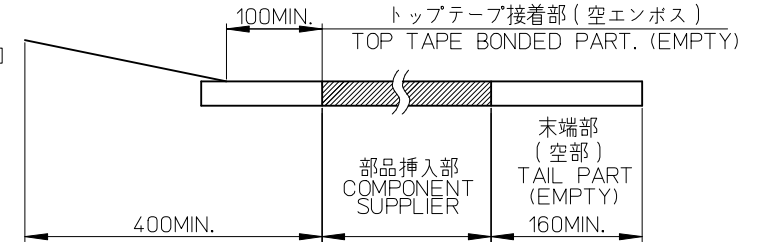
注記 NOTES

- 製品詳細寸法については図面 SD-503300-001 を参照下さい。
RE DETAILED DIMENSION, SEE SD-503300-001
- 梱包数量 : 3000 個/リール
NUMBER OF CONNECTORS : 3000 PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH

引き出し方向
PULL OUT
DIRECTION



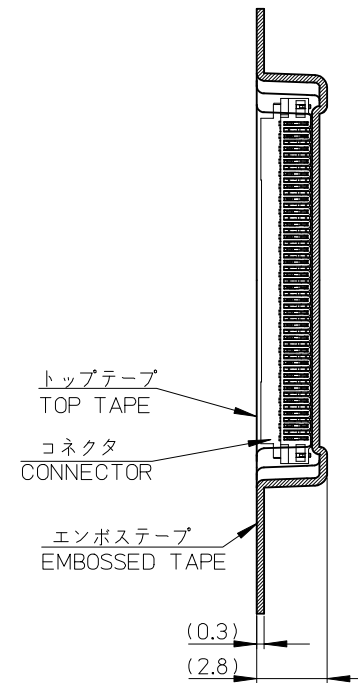
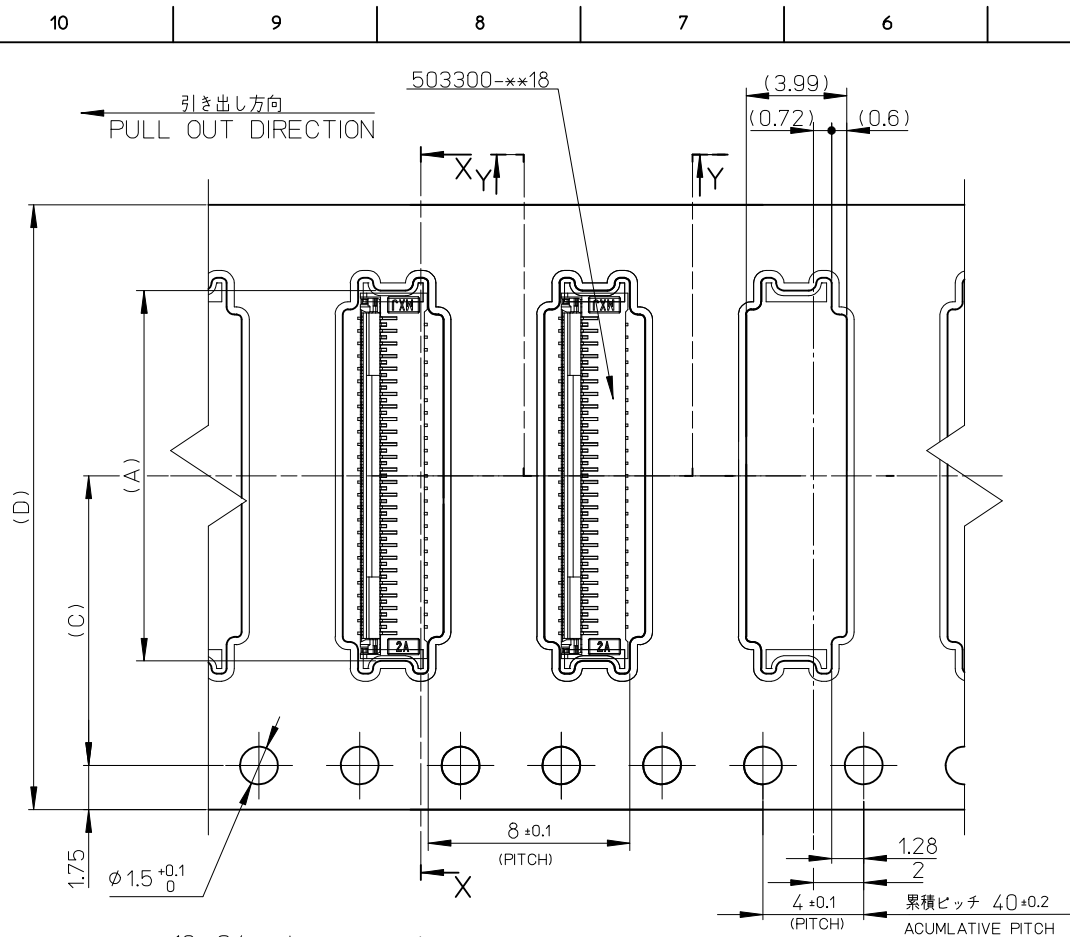
引き出し方向
PULL OUT
DIRECTION



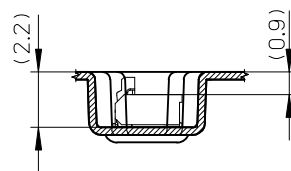
- 材料 MATERIAL
キャリアテープ (CARRIER TAPE) : ポリスチレン (POLYSTYRENE)
トップテープ (TOP TAPE) : PET , PE , PEF
リール (REEL) : ポリスチレン (PS) <リサイクル材を含む>
POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>
- カバーテープの剝離強度については、IEC60286-3 に準拠
COVER TAPE PEEL FORCE IS DEFINED BY IEC60286-3.

REVISED	EC NO: J2014-1201 DRWN: TMORISHITA 2014/01/29 CHKD: KATAHASHI 2014/01/29 APPR: YNOGAWA 2014/02/07	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	CONNECTOR SERIES NO. 503300- THIRD ANGLE PROJECTION	
			10 UNDER ±0.2	MNIITA 2010/08/24	TITLE 0.25MM FPC CONN. E/O H=1.2 HSG ASSY UPR EMBOSSED TAPE PACKAGE					
			10 OVER 30 UNDER ±0.25	CHECKED BY DATE SHOSHIKAWA 2010/08/24						
			30 OVER ±0.3	APPROVED BY DATE SHOSHIKAWA 2010/08/27	molex					
			ANGULAR ±1 °	MATERIAL NO.						DOCUMENT NO.
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-503300-002		1 OF 3	
					THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

molex



SECTION X-X



SECTION Y-Y

24	11.5	25.4	13.7	503300-4310	43
			13.2	503300-4110	41
			12.2	503300-3710	37
			10.7	503300-3110	31
			10.2	503300-2910	29
			8.2	503300-2110	21
(D) キャリアテープ幅 CARRIER TAPE WIDTH	(C)	B	(A)	オーダー番号 ORDER NO.	極数 CIRCUITS
CONNECTOR SERIES NO. 503300-**10					

REVISED EC NO: J2014-1201 DRWN: TMORISHITA CHKD: KTAHASHI APPR: YNOGAWA 2014/01/29 2014/01/29 2014/02/07	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY MNIITA	DATE 2010/08/24	TITLE 0.25MM FPC CONN. E/O H=1.2 HSG ASSY UPR EMBOSSED TAPE PACKAGE molex				
		10 OVER 30 UNDER	± 0.25	CHECKED BY SHOSHIKAWA	DATE 2010/08/24					
		30 OVER	± 0.3	APPROVED BY SHOSHIKAWA	DATE 2010/08/27					
		ANGULAR ±1 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-503300-002		2 OF 3			
REV		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								

